LM741 Operational Amplifier

Check for Samples: LM741

FEATURES

- **Overload Protection on the Input and Output**
- **No Latch-Up When the Common Mode Range is Exceeded**

DESCRIPTION

The LM741 series are general purpose operational amplifiers which feature improved performance over industry standards like the LM709. They are direct, plug-in replacements for the 709C, LM201, MC1439 and 748 in most applications.

The amplifiers offer many features which make their application nearly foolproof: overload protection on the input and output, no latch-up when the common mode range is exceeded, as well as freedom from oscillations.

The LM741C is identical to the LM741/LM741A except that the LM741C has their performance ensured over a 0°C to +70°C temperature range, instead of −55°C to +125°C.

Connection Diagrams

LM741H is available per JM38510/10101

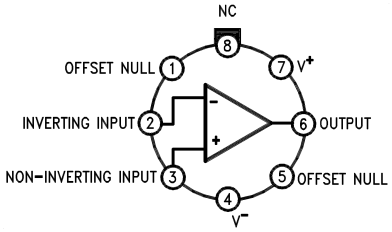


Figure 1. TO-99 Package
See Package Number LMC0008C

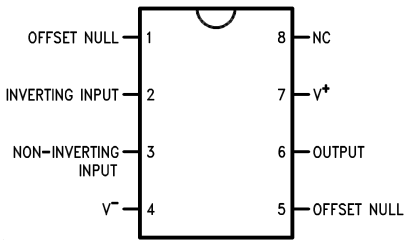


Figure 2. CDIP or PDIP Package
See Package Number NAB0008A, P0008E

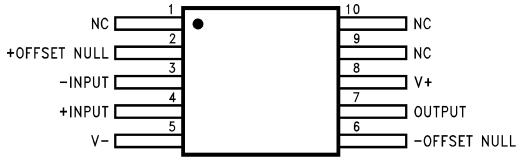


Figure 3. CLGA Package
See Package Number NAD0010A

Typical Application

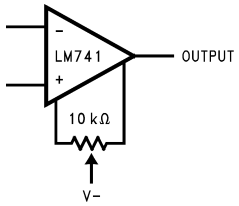


Figure 4. Offset Nulling Circuit

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings(1)(2)(3)

	LM741A	LM741	LM741C
Supply Voltage	±22V	±22V	±18V
Power Dissipation (4)	500 mW	500 mW	500 mW
Differential Input Voltage	±30V	±30V	±30V
Input Voltage (5)	±15V	±15V	±15V
Output Short Circuit Duration	Continuous	Continuous	Continuous
Operating Temperature Range	−55°C to +125°C	−55°C to +125°C	0°C to +70°C
Storage Temperature Range	−65°C to +150°C	−65°C to +150°C	−65°C to +150°C
Junction Temperature	150°C	150°C	100°C
Soldering Information			
P0008E-Package (10 seconds)	260°C	260°C	260°C
NAB0008A- or LMC0008C-Package (10 seconds)	300°C	300°C	300°C
M-Package			
Vapor Phase (60 seconds)	215°C	215°C	215°C
Infrared (15 seconds)	215°C	215°C	215°C
ESD Tolerance (6)	400V	400V	400V

(1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.
(2) For military specifications see RETS741X for LM741 and RETS741AX for LM741A.
(3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
(4) For operation at elevated temperatures, these devices must be derated based on thermal resistance, and T_j max. (listed under "Absolute Maximum Ratings"). $T_j = T_A + (\theta_{jA} P_D)$.
(5) For supply voltages less than ±15V, the absolute maximum input voltage is equal to the supply voltage.
(6) Human body model, 1.5 kΩ in series with 100 pF.

Electrical Characteristics(1)

Parameter	Test Conditions	LM741A			LM741			LM741C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage	T_A = 25°C $R_S \le 10$ kΩ $R_S \le 50$Ω		0.8	3.0		1.0	5.0		2.0	6.0	mV
	$T_{AMIN} \le T_A \le T_{AMAX}$ $R_S \le 50$Ω $R_S \le 10$ kΩ			4.0			6.0			7.5	mV
Average Input Offset Voltage Drift				15							µV/°C

(1) Unless otherwise specified, these specifications apply for V_S = ±15V, −55°C ≤ T_A ≤ +125°C (LM741/LM741A). For the LM741C/LM741E, these specifications are limited to 0°C ≤ T_A ≤ +70°C.

Electrical Characteristics[1] (continued)

Parameter	Test Conditions	LM741A			LM741			LM741C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage Adjustment Range	T_A = 25°C, V_S = ±20V	±10				±15			±15		mV
Input Offset Current	T_A = 25°C		3.0	30		20	200		20	200	nA
	$T_{AMIN} \le T_A \le T_{AMAX}$			70		85	500			300	
Average Input Offset Current Drift				0.5							nA/°C
Input Bias Current	T_A = 25°C		30	80		80	500		80	500	nA
	$T_{AMIN} \le T_A \le T_{AMAX}$			0.210			1.5			0.8	µA
Input Resistance	T_A = 25°C, V_S = ±20V	1.0	6.0		0.3	2.0		0.3	2.0		MΩ
	$T_{AMIN} \le T_A \le T_{AMAX}$, V_S = ±20V	0.5									
Input Voltage Range	T_A = 25°C							±12	±13		V
	$T_{AMIN} \le T_A \le T_{AMAX}$				±12	±13					
Large Signal Voltage Gain	T_A = 25°C, $R_L \ge 2$ kΩ										V/mV
	V_S = ±20V, V_O = ±15V	50									
	V_S = ±15V, V_O = ±10V				50	200		20	200		
	$T_{AMIN} \le T_A \le T_{AMAX}$, $R_L \ge 2$ kΩ,										V/mV
	V_S = ±20V, V_O = ±15V	32									
	V_S = ±15V, V_O = ±10V				25			15			
	V_S = ±5V, V_O = ±2V	10									
Output Voltage Swing	V_S = ±20V										V
	$R_L \ge 10$ kΩ	±16									
	$R_L \ge 2$ kΩ	±15									
	V_S = ±15V										V
	$R_L \ge 10$ kΩ				±12	±14		±12	±14		
	$R_L \ge 2$ kΩ				±10	±13		±10	±13		
Output Short Circuit Current	T_A = 25°C	10	25	35		25			25		mA
	$T_{AMIN} \le T_A \le T_{AMAX}$	10		40							
Common-Mode Rejection Ratio	$T_{AMIN} \le T_A \le T_{AMAX}$										dB
	$R_S \le 10$ kΩ, V_{CM} = ±12V				70	90		70	90		
	$R_S \le 50$Ω, V_{CM} = ±12V	80	95								
Supply Voltage Rejection Ratio	$T_{AMIN} \le T_A \le T_{AMAX}$,										dB
	V_S = ±20V to V_S = ±5V										
	$R_S \le 50$Ω	86	96								
	$R_S \le 10$ kΩ				77	96		77	96		
Transient Response	T_A = 25°C, Unity Gain										
Rise Time			0.25	0.8		0.3			0.3		µs
Overshoot			6.0	20		5			5		%
Bandwidth [2]	T_A = 25°C	0.437	1.5								MHz
Slew Rate	T_A = 25°C, Unity Gain	0.3	0.7			0.5			0.5		V/µs
Supply Current	T_A = 25°C					1.7	2.8		1.7	2.8	mA
Power Consumption	T_A = 25°C										mW
	V_S = ±20V		80	150							
	V_S = ±15V					50	85		50	85	

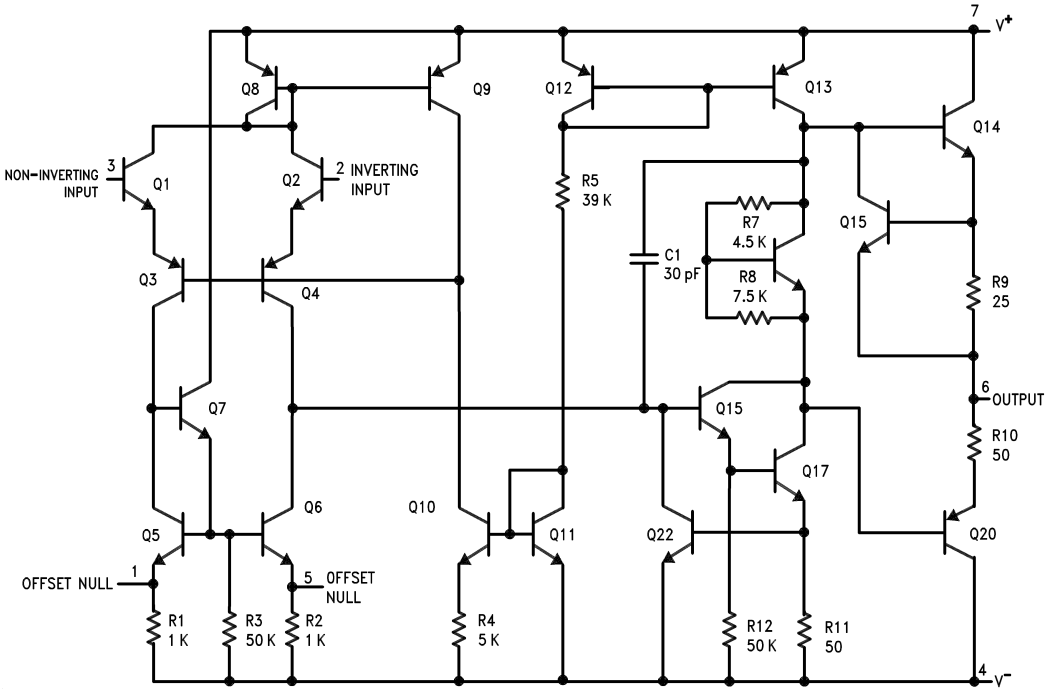
(2) Calculated value from: BW (MHz) = 0.35/Rise Time (µs).

Electrical Characteristics[1] (continued)

Parameter	Test Conditions	LM741A			LM741			LM741C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
LM741A	V_S = ±20V										
	$T_A = T_{AMIN}$			165							mW
	$T_A = T_{AMAX}$			135							
LM741	V_S = ±15V										
	$T_A = T_{AMIN}$					60	100				mW
	$T_A = T_{AMAX}$					45	75				

Thermal Resistance	CDIP (NAB0008A)	PDIP (P0008E)	TO-99 (LMC0008C)	SO-8 (M)
θ_{jA} (Junction to Ambient)	100°C/W	100°C/W	170°C/W	195°C/W
θ_{jC} (Junction to Case)	N/A	N/A	25°C/W	N/A

SCHEMATIC DIAGRAM



REVISION HISTORY

Changes from Revision B (March 2013) to Revision C	Page
• Changed layout of National Data Sheet to TI format	4

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM741CH	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	0 to 70	LM741CH	Samples
LM741CH/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	0 to 70	LM741CH	Samples
LM741CN	ACTIVE	PDIP	P	8	40	TBD	Call TI	Call TI	0 to 70	LM 741CN	Samples
LM741CN/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM 741CN	Samples
LM741H	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	-55 to 125	LM741H	Samples
LM741H/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM741H	Samples
LM741J	ACTIVE	CDIP	NAB	8	40	TBD	Call TI	Call TI	-55 to 125	LM741J	Samples
U5B7741312	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	-55 to 125	LM741H	Samples
U5B7741393	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	0 to 70	LM741CH	Samples
U9T7741393	NRND	PDIP	P	8	40	TBD	Call TI	Call TI	0 to 70	LM 741CN	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

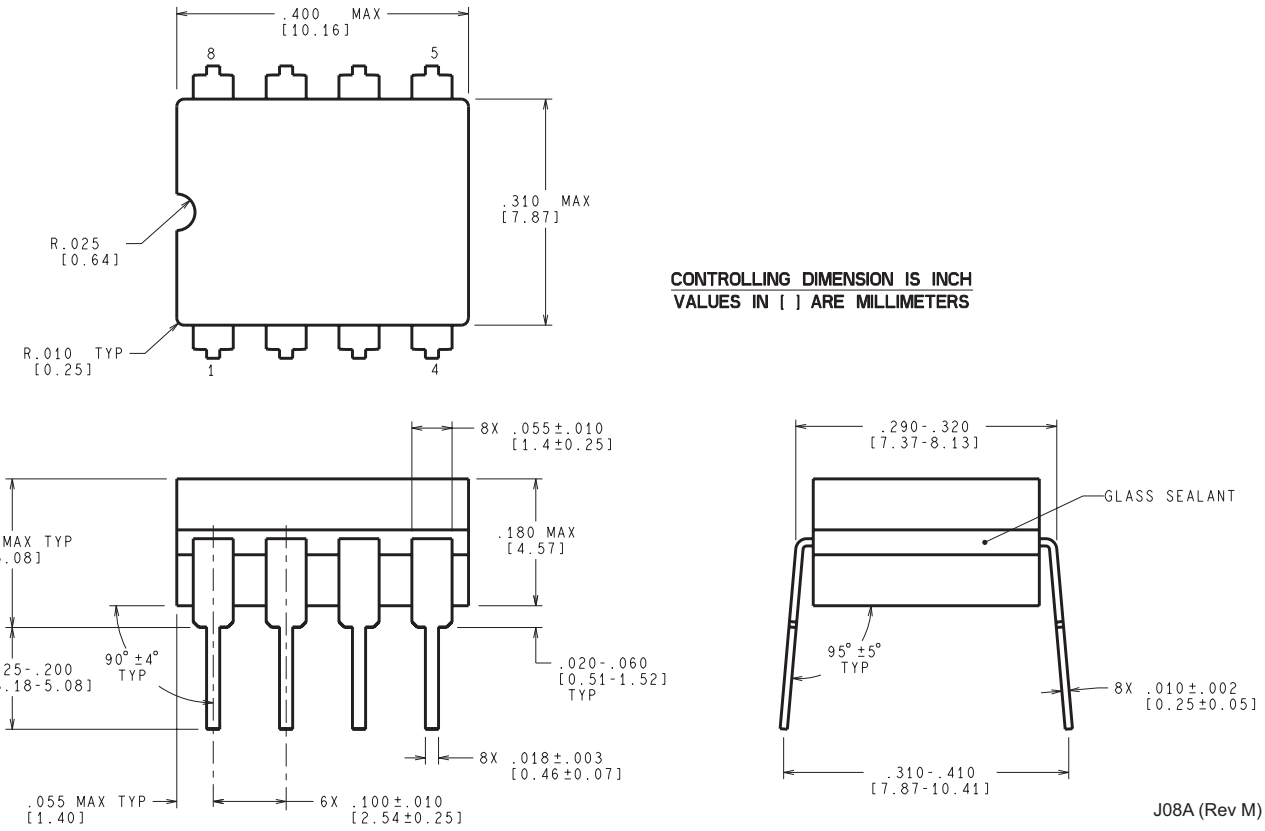
(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

NAB0008A


.400 MAX
[10.16]
8
5
.310 MAX
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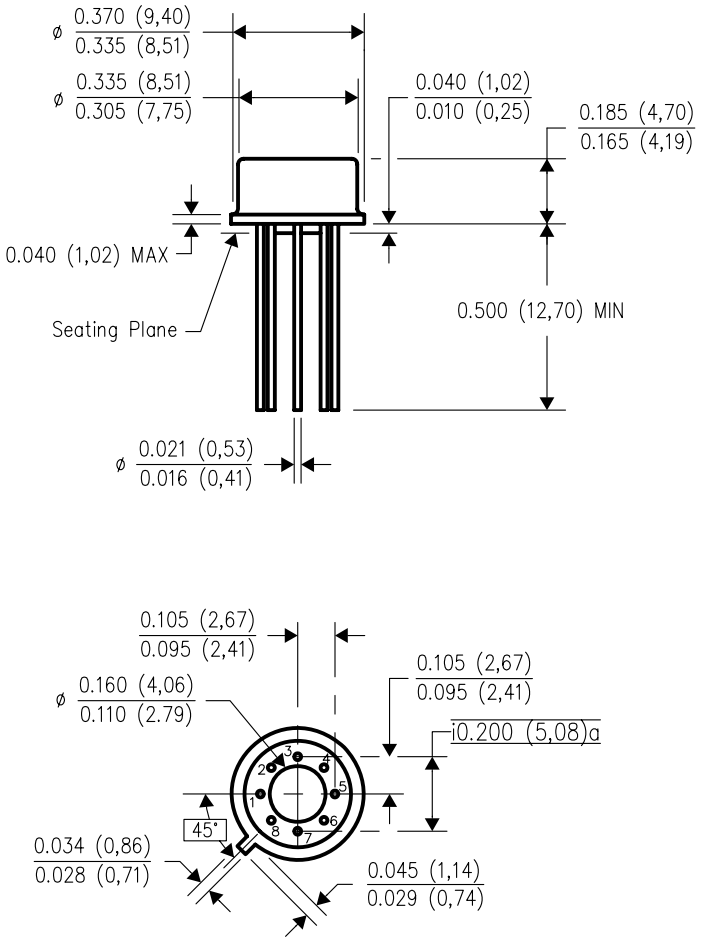
R.025
[0.64]
R.010 TYP
[0.25]
1
4
CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS
8X .055±.010
[1.4±0.25]
.200 MAX TYP
[5.08]
.180 MAX
[4.57]
8X .125-.200
[3.18-5.08]
90° ±4°
TYP
.020-.060
[0.51-1.52]
TYP
8X .018±.003
[0.46±0.07]
.055 MAX TYP
[1.40]
6X .100±.010
[2.54±0.25]
.290-.320
[7.37-8.13]
GLASS SEALANT
95° ±5°
TYP
8X .010±.002
[0.25±0.05]
.310-.410
[7.87-10.41]
J08A (Rev M)

LMC (O–MBCY–W8) METAL CYLINDRICAL PACKAGE



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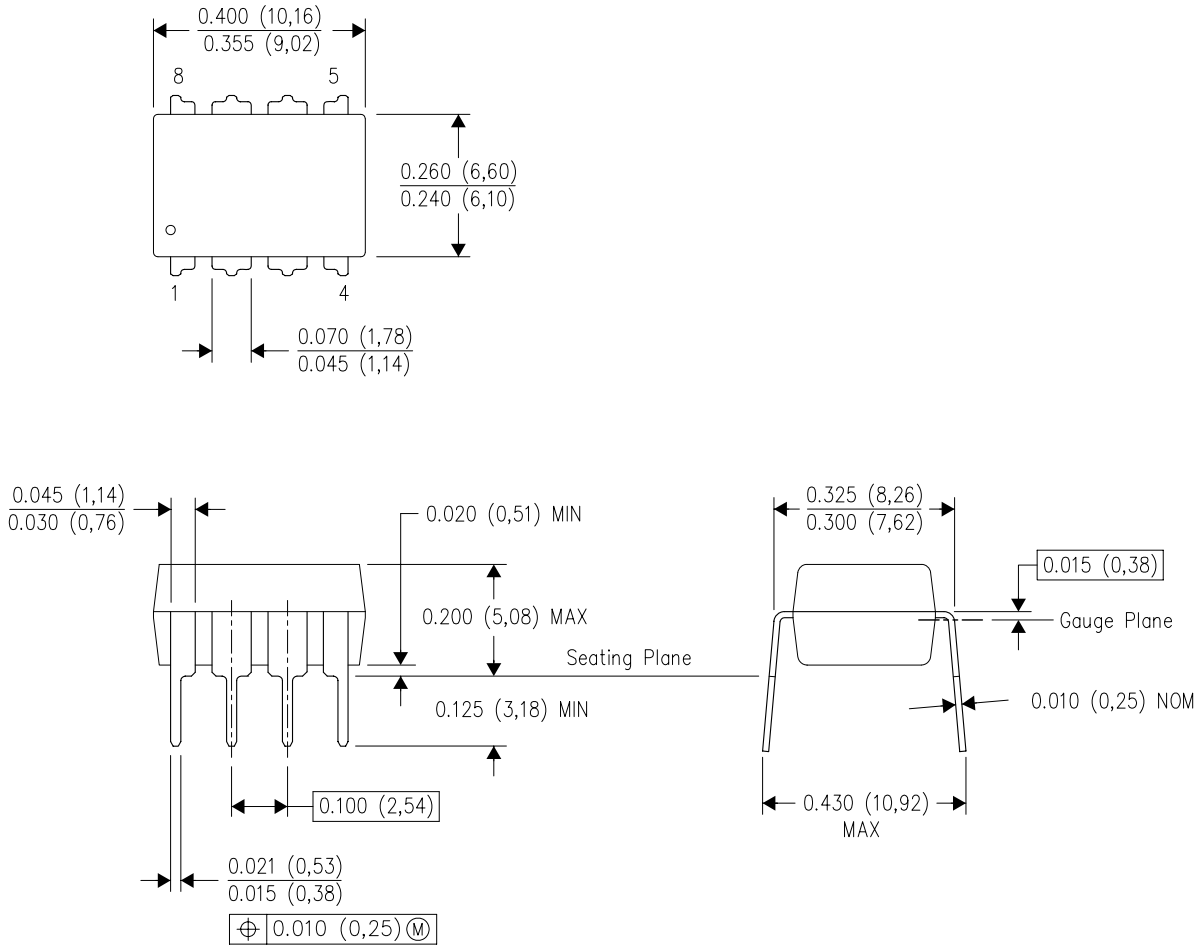
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Leads in true position within 0.010 (0,25) R @ MMC at seating plane.
D. Pin numbers shown for reference only. Numbers may not be marked on package.
E. Falls within JEDEC MO–002/TO–99.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

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